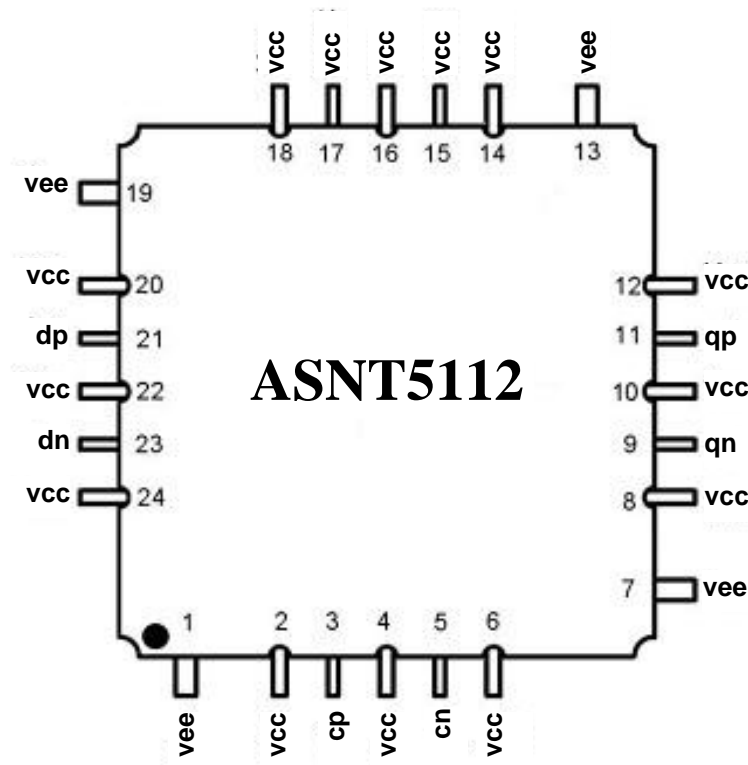




ASNT5112-KMC DC-32Gbps High Sensitivity D-Type Flip-Flop

- High speed broadband D-Type Flip-Flop for data retiming with full rate clock
- Sensitive input data buffer with increased common-mode voltage range to support sampling applications
- Exhibits low jitter and limited temperature variation over industrial temperature range
- 4ps set-up/hold time capability
- 88% clock phase margin for retiming of data input eye
- Fully differential CML input interfaces
- Fully differential CML output interface with 400mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 345mW
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 24-pin package



DESCRIPTION

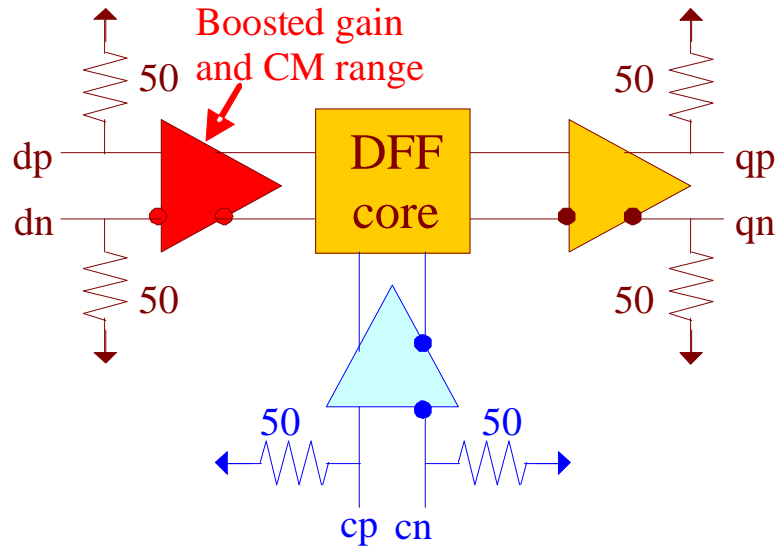


Fig. 1. Functional Block Diagram

The temperature stable ASNT5112-KMC SiGe IC provides broadband data retiming functionality and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can sample the high-speed data signal dp/dn with the full-rate external clock cp/cn to create the full-rate retimed NRZ data output qp/qn .

The data input buffer is designed to have increased input signal sensitivity and is able to operate over a wider range of input common mode (CM) voltages. The part's I/O's support the CML logic interface with on chip 50Ω termination to vcc and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either negative supply ($vcc = 0.0V = \text{ground}$ and $vee = -3.3V$), or positive supply ($vcc = +3.3V$ and $vee = 0.0V = \text{ground}$). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50Ω termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume $vcc = 0.0V$ and $vee = -3.3V$.



ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed vcc).

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.38	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
High-Speed I/Os			
dp	21	CML input	Differential high-speed data inputs with internal SE 50Ohm termination to vcc.
dn	23		
cp	3	CML input	Differential high-speed clock inputs with internal SE 50Ohm termination to vcc.
cn	5		
qp	11	CML output	Differential high-speed full-rate data outputs. Require external SE 50Ohm termination to vcc.
qn	9		
Supply and Termination Voltages			
Name	Description		Pin Number
vcc	Positive power supply. (+3.3V or 0V)		2, 4, 6, 8, 10, 12, 14, 15, 16, 17, 18, 20, 22, 24
vee	Negative power supply. (0V or -3.3V)		1, 7, 13, 19



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
I _{vee}		105		mA	
Power consumption		345		mW	
Junction temperature	-40	25	125	°C	
Input Data (dp/dn)					
Data Rate	DC		32	Gbps	
Swing	0.05		0.8	V	Differential or SE, p-p
CM voltage level	vcc-1.5	vcc -0.3	vcc	V	Must match for both inputs
Input Clock (cp/cn)					
Frequency	DC		32	GHz	
Swing	0.05		0.8	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
Duty cycle	40	50	60	%	
Clock phase margin	86	88	90	%	For reliable data latching
HS Output Data (qp/qn)					
Data Rate	DC		32	Gbps	
Logic "1" level		vcc		V	
Logic "0" level		vcc-0.4		V	With external 50Ωm DC termination
Rise/Fall times			13	ps	20%-80%
Output Jitter			2.5	ps	Peak-to-peak

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package shown in Fig. 2. Even though the package provides a center heat slug located on the back side of the package to be used for heat dissipation, ADSANTEC does **NOT** recommend for this section to be soldered to the board. If the customer wishes to solder it, it should be connected to the vcc plain that is ground for the negative supply or power for the positive supply.

The part's identification label is ASNT5112-KMC. The first 8 characters of the name before the underscore identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per EU 2002/95/EC for all six substances.

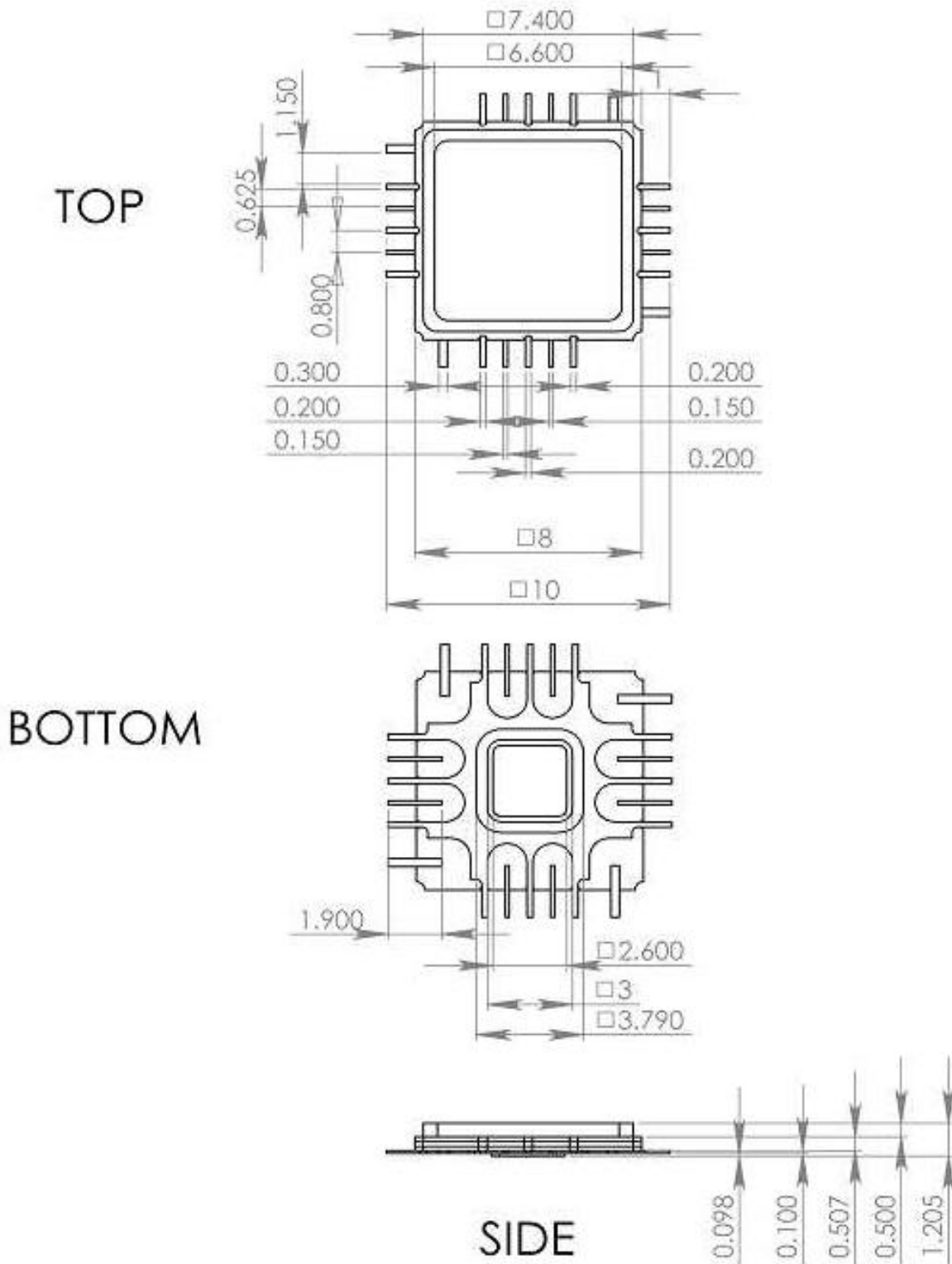


Fig. 2. CQFP 24-Pin Package Drawing (All Dimensions in mm)



REVISION HISTORY

Revision	Date	Changes
3.5.1	02-2013	Revised terminal functions Revised electrical characteristics section
3.4.1	02-2013	Revised title Revised package pin out drawing Revised functional block diagram Revised description Revised terminal functions Revised electrical characteristics section Revised package information section
3.3.1	01-2013	Corrected pin out drawing Revised electrical characteristics section Corrected phase margin specification
3.2.1	01-2013	Corrected format Added package drawing Corrected absolute maximum ratings table
3.1	02-2012	Revised power supply configuration section Revised package information section
3.0	01-2012	Added power supply configuration text Added absolute maximum ratings table Revised electrical characteristics section Revised package information section
2.0	02-2009	Revised electrical characteristics section Revised package information section
1.0	01-2009	First release